

Customer No.: 31561
Application No.: 10/711,540
Docket No.: 13365-US-PA

AMENDMENT

To the Claims:

1-24 (cancelled).

25. (original) A chip with polymer thereon, comprising at least:

a chip having an active surface; and

a polymer, disposed at periphery of the active surface of the chip extending to sidewalls of the chip.

26. (original) The chip with polymer thereon of claim 25, further comprising a plurality of wires electrically connecting the chip and a carrier for carrying the chip.

27. (original) The chip with polymer thereon of claim 26, wherein the polymer further covers a portion of each wire near the active surface of the chip.

28. (original) The chip with polymer thereon of claim 26, wherein the polymer further covers a portion of the carrier.

29. (original) The chip with polymer thereon of claim 26, wherein the carrier comprises a leadframe or a circuit substrate.

30. (original) The electrical package structure of claim 25, wherein the polymer is shaped as a ring covering whole periphery of the active surface of the chip.

31. (original) The electrical package structure of claim 25, wherein the polymer is shaped as strips covering two opposite edges of the active surface of the chip.

32. (original) The electrical package structure of claim 25, wherein the polymer is shaped as a plurality of pieces covering four corners of the active surface of the chip.

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33. (original) The electrical package structure of claim 25, wherein the polymer comprises a stress buffer polymer.

34. (original) The electrical package structure of claim 33, wherein the stress buffer polymer comprises epoxy resin or polyimide.